



**THE DATASHEET OF
CIM05U221NC**



Chip Bead For EMI Suppression

CIB/CIM05 Series (1005/ EIA 0402)



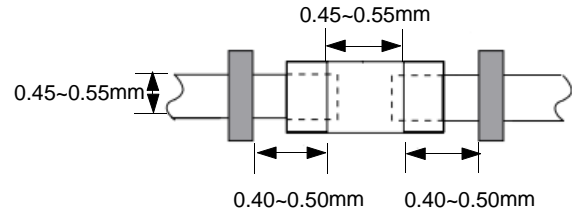
APPLICATION

High frequency EMI prevention application to computers, printers, VCRs, TVs and mobile phones.

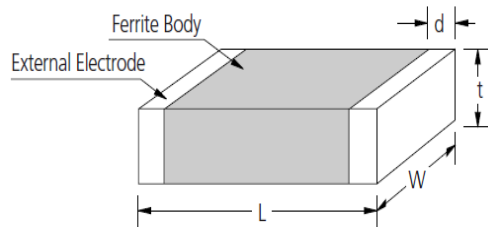
FEATURES

- Perfect shape for automatic mounting, with no directionality.
- Excellent solderability and high heat resistance for either flow or reflow soldering
- Monolithic inorganic material construction for high reliability
- Closed magnetic circuit configuration avoids crosstalk and is suitable for high density PCBs.

RECOMMENDED LAND PATTERN



DIMENSION



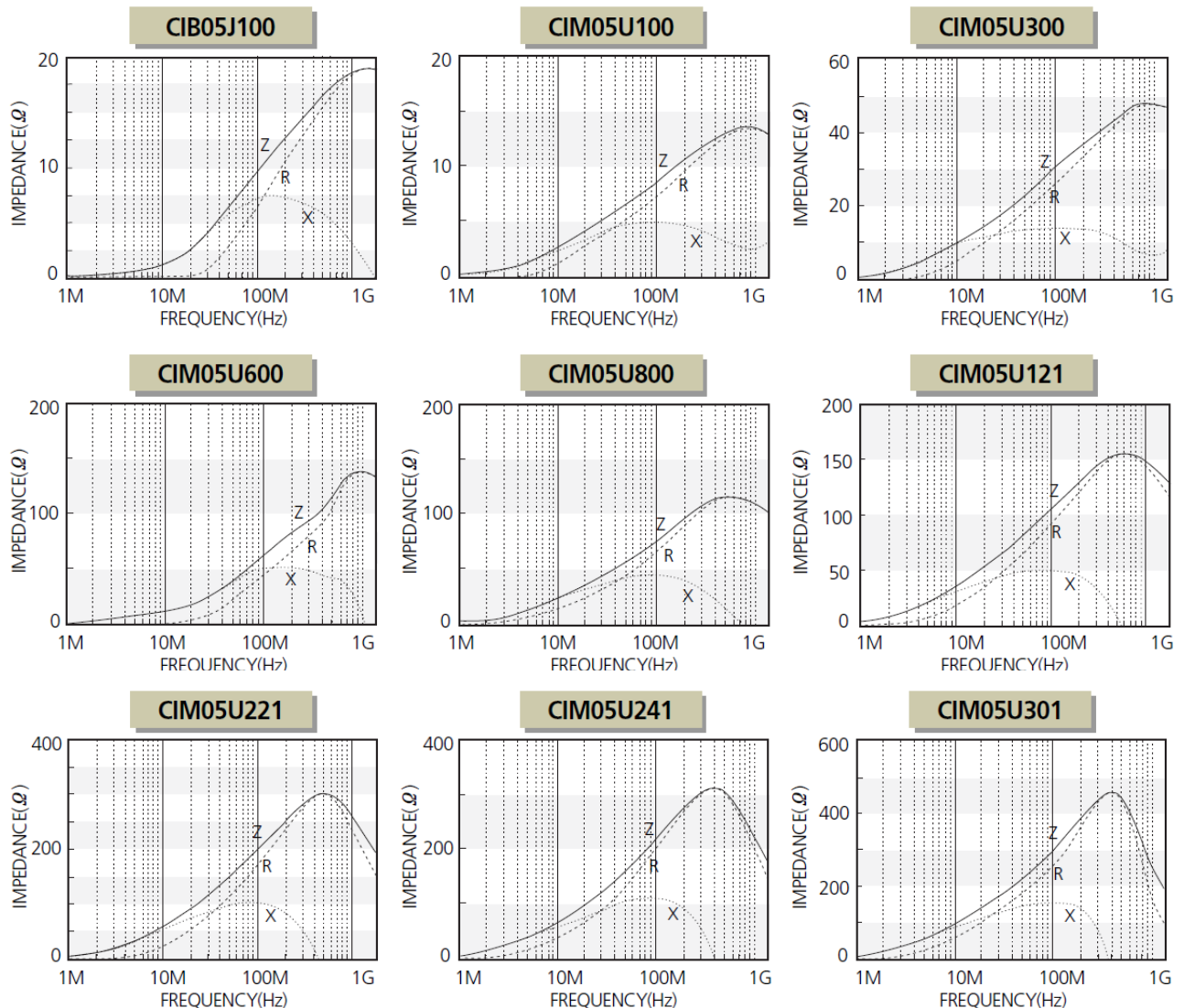
Type	Dimension [mm]			
	L	W	t	d
05	1.0±0.05	0.5±0.05	0.5±0.05	0.25±0.1

DESCRIPTION

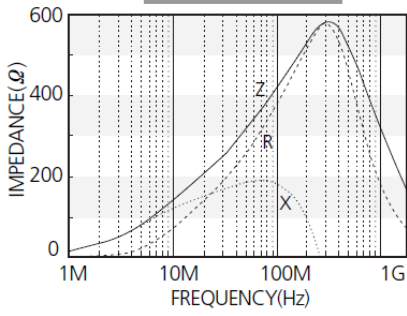
Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIB05J100	0.5±0.05	10	0.05	1200
CIM05U100	0.5±0.05	10	0.05	1200
CIM05U300	0.5±0.05	30	0.10	700
CIM05U600	0.5±0.05	60	0.15	600
CIM05U800	0.5±0.05	80	0.20	600
CIM05U121	0.5±0.05	120	0.25	600
CIM05U221	0.5±0.05	220	0.35	500
CIM05U241	0.5±0.05	240	0.35	400
CIM05U301	0.5±0.05	300	0.45	400
CIM05U471	0.5±0.05	470	0.55	300
CIM05U601	0.5±0.05	600	0.60	300
CIM05U102	0.5±0.05	1000	0.80	300
CIM05J300	0.5±0.05	30	0.20	700
CIM05J600	0.5±0.05	60	0.20	650
CIM05J800	0.5±0.05	80	0.25	600
CIM05J121	0.5±0.05	120	0.25	500
CIM05J221	0.5±0.05	220	0.35	400
CIM05J241	0.5±0.05	240	0.35	400
CIM05J301	0.5±0.05	300	0.45	400
CIM05J471	0.5±0.05	470	0.55	300
CIM05J601	0.5±0.05	600	0.60	300

Part no.	Thickness (mm)	Impedance (Ω) \pm 25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIM05J102	0.5 \pm 0.05	1000	0.80	250
CIM05J152	0.5 \pm 0.05	1500	1.00	250
CIM05J182	0.5 \pm 0.05	1800	1.40	200
CIM05N750	0.5 \pm 0.05	75	0.35	300
CIM05N121	0.5 \pm 0.05	120	0.55	300
CIM05N221	0.5 \pm 0.05	220	0.80	200
CIM05F050	0.5 \pm 0.05	5	0.08	500
CIM05F100	0.5 \pm 0.05	10	0.10	300
CIM05F220	0.5 \pm 0.05	22	0.20	300
CIM05F470	0.5 \pm 0.05	47	0.35	300
CIM05F750	0.5 \pm 0.05	75	0.40	300
CIM05F121	0.5 \pm 0.05	120	0.55	300
CIM05F221	0.5 \pm 0.05	220	0.80	200
CIM05H800	0.5 \pm 0.05	80	0.20	450
CIM05H121	0.5 \pm 0.05	120	0.25	400
CIM05H601	0.5 \pm 0.05	600	0.80	200

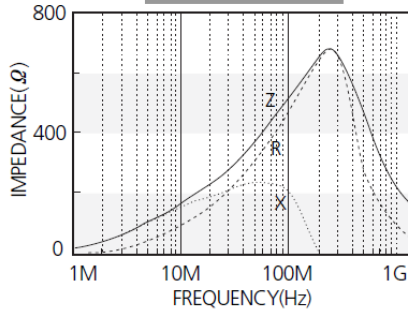
CHARACTERISTIC DATA



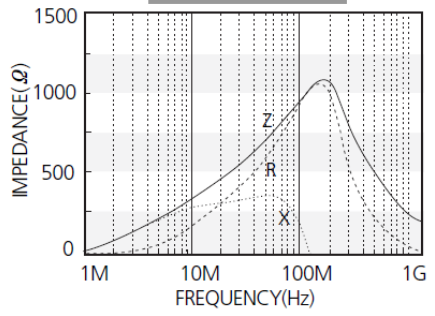
CIM05U471



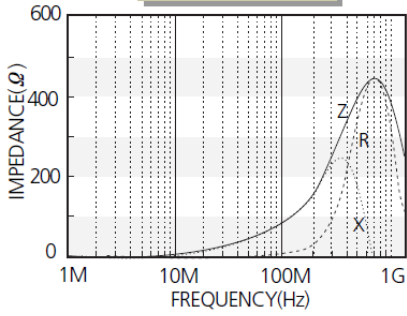
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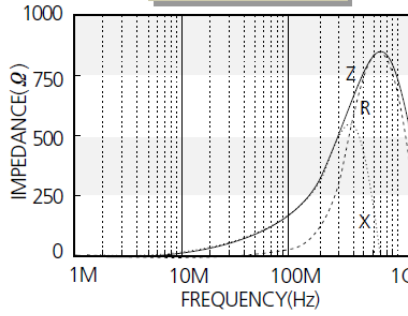
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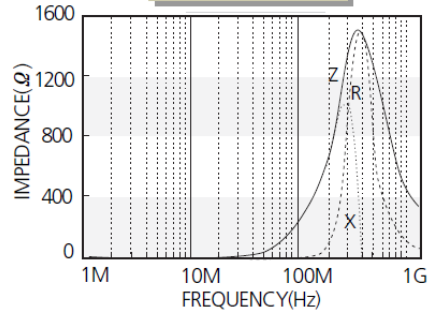
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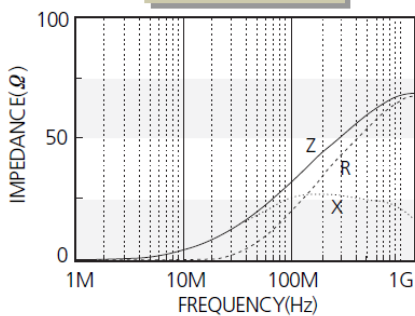
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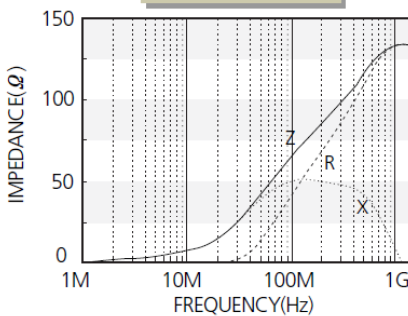
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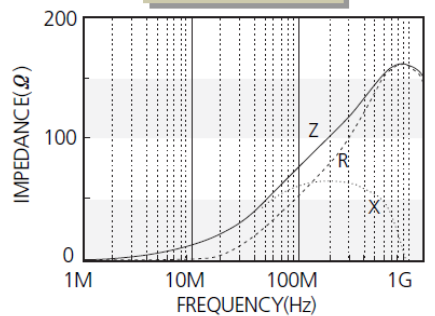
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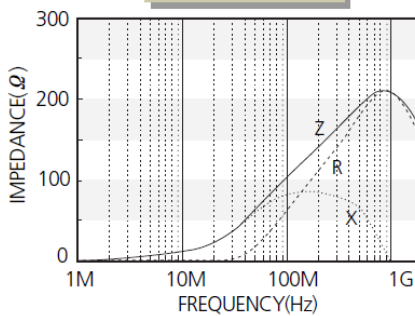
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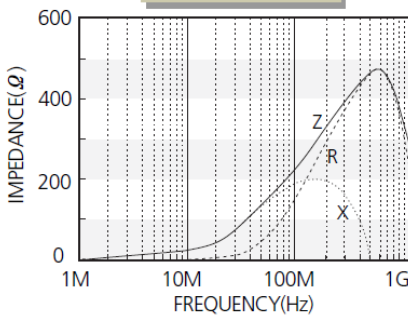
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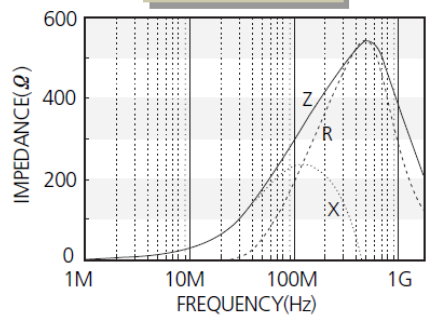
CIM05J121



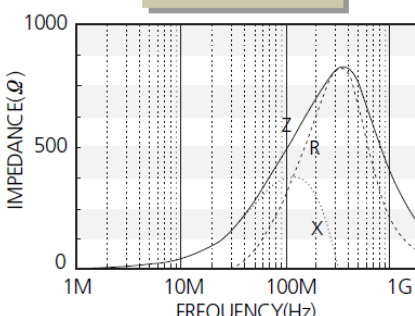
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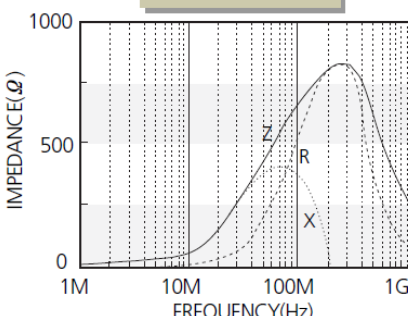
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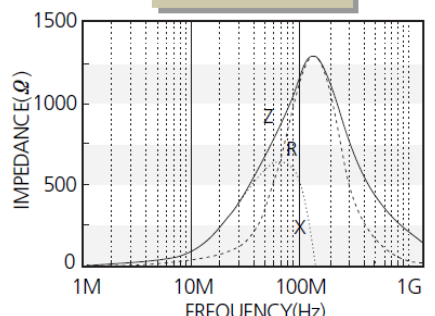
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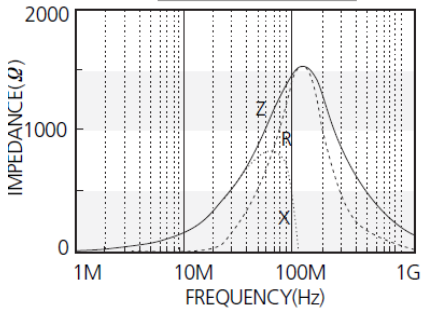
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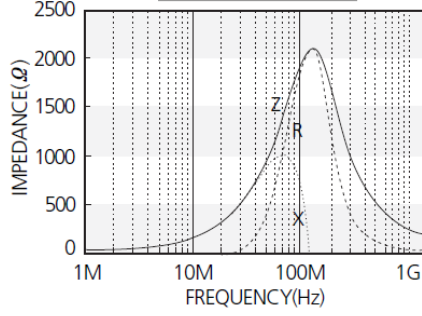
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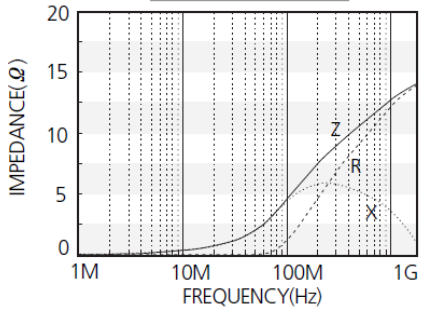
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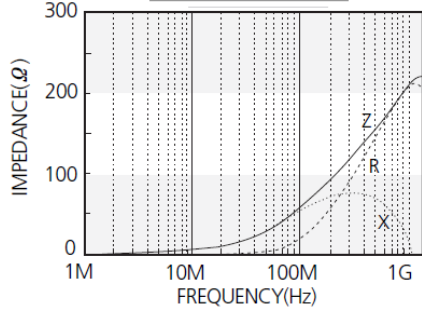
CIM05J182



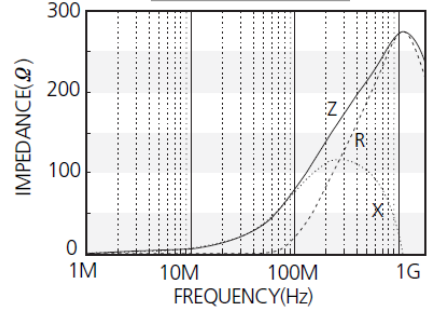
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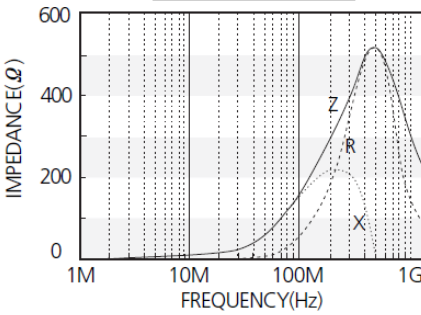
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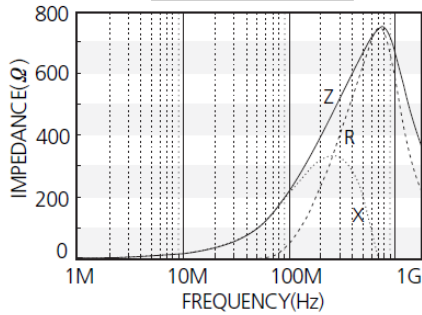
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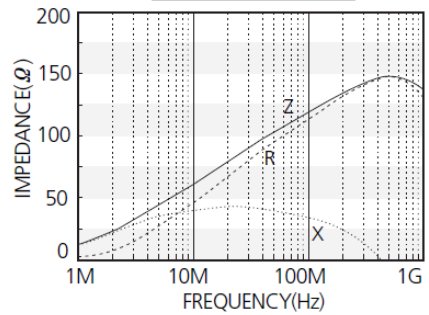
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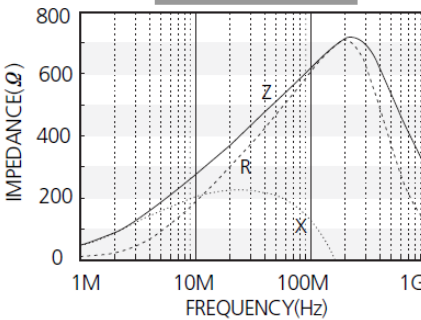
CIM05F221



CIM05H121



CIM05H601



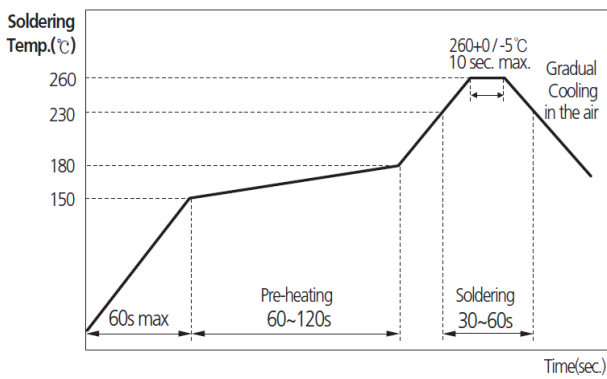
PRODUCT IDENTIFICATION

CI M 05 U 121 N C
(1) (2) (3) (4) (5) (6) (7)

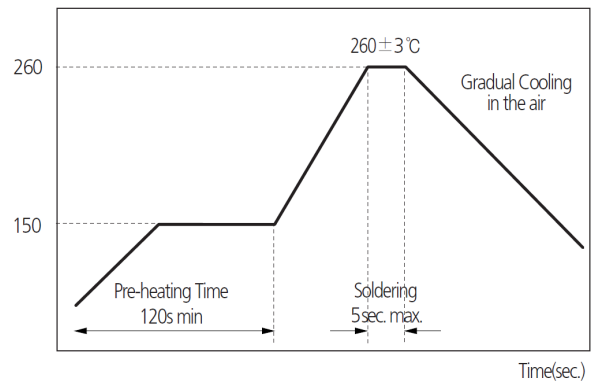
- (1) Chip Beads
- (2) M: Multi-layer type B:Mono-layer type
- (3) Dimension
- (4) Material Code
- (5) Nominal impedance (100:10Ω, 121:120Ω)
- (6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (7) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	10,000

Any data in this sheet are subject to change, modify or discontinue without notice.
The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.

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-  Alternative Solution
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